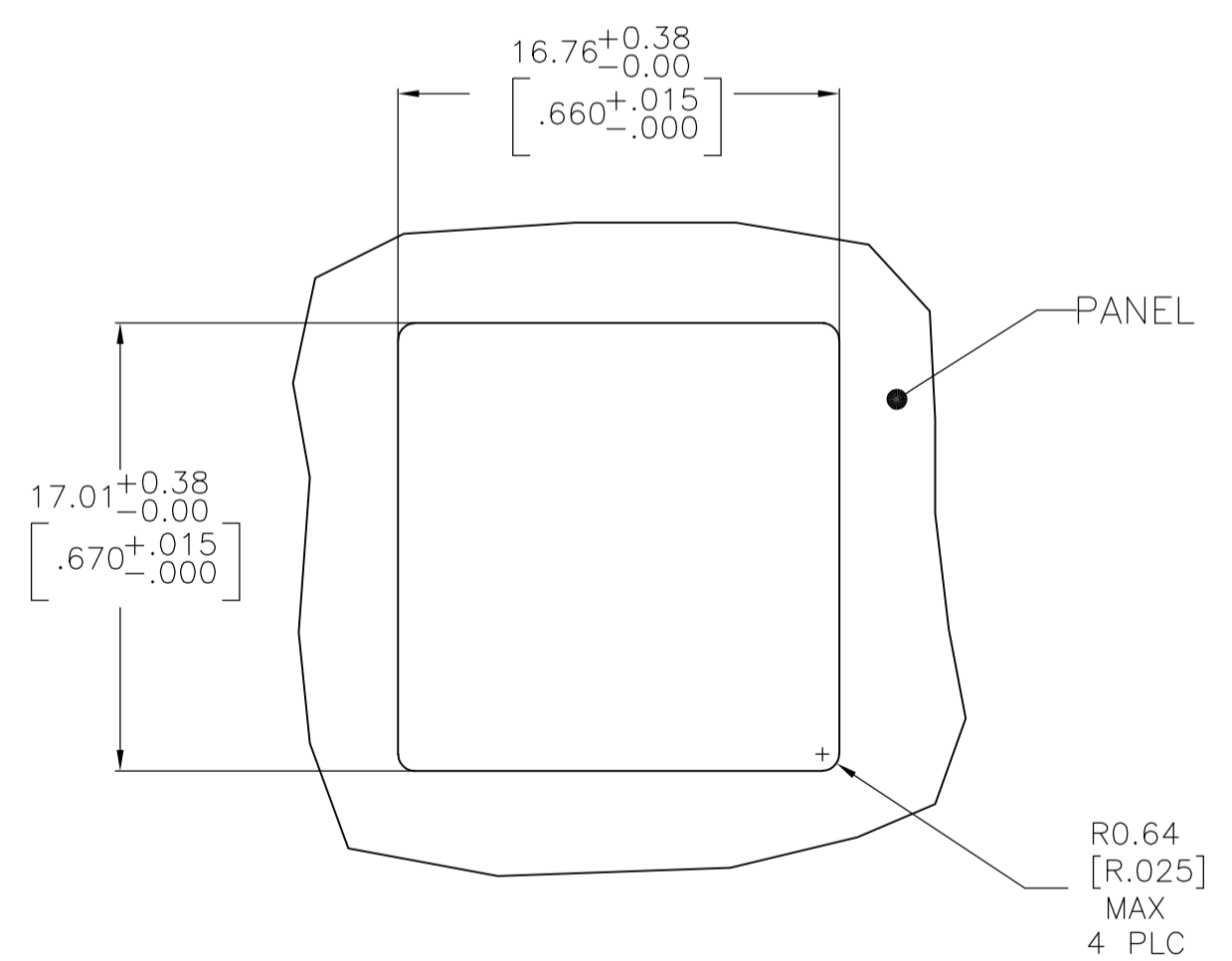


RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

2.79-3.30 [.120±.010]	5557969-2
2.79-3.56 [.125±.015]	5557969-1
DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN A FERNANDEZ-DOCKS 06JUN2005		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 06JUN2005		NAME S. FLICKINGER 06JUN2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-1163		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL	
0 PLC ± -		APPLICATION SPEC 114-2048		SIZE 114-2048	
1 PLC ± -		DRAWING NO. 00779		RESTRICTED TO	
2 PLC ± 0.13[.005]		SCALE 4:1		SHEET 1 OF 1	
3 PLC ± -		REV 1		REV D1	
4 PLC ± -		CUSTOMER DRAWING			